ASSOCIATION CONNECTION ELECTRONICS INDUSTRI	© Copyright 2005, IPC, 1	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						als and Mf	g Inform	nation	
Supplier Infori	mation														
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
nsemi												2023-06-08			
Contact Name		Title - Contact			I	Phone - Contact*					Email - Contact*				
Product-Env-Stew	vards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorized Repres	sentative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Reques	ester Item Number Mfr Iter		Number	Mfr Item Name				te Versio	Version M		Manufacturing Site		eight*	UOM	Unit Type
		MC14051BDTR2G LOG C		LOG CMOS ML	OG CMOS MLTIPLXR 8CHAN		2023-06-08 PH		PH1		4:	45.4 mg		Each	
	g Proccess Information									Ļ					
Termina	l Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 MS	20 MSL Rating		Peak Process Body Temperature		e Max Ti	me at Peak	Temperatu	re Nur	mber of Reflow Cyc	les
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		ı) (no C	CU Alloy 1		1		260		C 30			seconds 3			
Comments															
vel 1 - maximum	time at peak temperature d	luring sol	dering is 10-3	0 seconds											
or more informat	tion regarding material com	position 1	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.0	mg	Supplier	Silicon (Si)	7440-21-3		2	mg
Die Attach	1.32	mg		Epoxy resin	proprietary data		0.3036	mg
			Supplier	Silver (Ag)	7440-22-4		1.0164	mg
Lead Frame	20.76	mg	Supplier	Silver (Ag)	7440-22-4		0.0623	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0394	mg
			Supplier	Iron (Fe)	7439-89-6		0.5377	mg
			Supplier	Copper (Cu)	7440-50-8		20.0915	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0291	mg
Mold Compound-Black	19.0	mg		Epoxy resin	proprietary data		0.95	mg
			Supplier	Phenol Resin	Proprietary Data		0.76	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.9	mg
			Supplier	Carbon Black (C)	1333-86-4		0.19	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		15.2	mg
Plating	2.12	mg	Supplier	Palladium (Pd)	7440-05-3		0.1611	mg
			В	Nickel (Ni)	7440-02-0		1.9292	mg
			Supplier	Gold (Au)	7440-57-5		0.0297	mg
Wire Bond	0.2	mg	Supplier	Palladium (Pd)	7440-05-3		0.002	mg
			Supplier	Copper (Cu)	7440-50-8		0.198	mg